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### Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

#### Details

Product Status	Obsolete
Number of LABs/CLBs	172600
Number of Logic Elements/Cells	457000
Total RAM Bits	39936000
Number of I/O	552
Number of Gates	-
Voltage - Supply	0.82V ~ 0.88V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1152-BBGA, FCBGA
Supplier Device Package	1152-FBGA (35x35)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/intel/5sgsmd5h3f35i3l">https://www.e-xfl.com/product-detail/intel/5sgsmd5h3f35i3l</a>

**Table 1. Stratix V GX and GS Commercial and Industrial Speed Grade Offering <sup>(1), (2), (3)</sup> (Part 2 of 2)**

Transceiver Speed Grade	Core Speed Grade							
	C1	C2, C2L	C3	C4	I2, I2L	I3, I3L	I3YY	I4
3 GX channel—8.5 Gbps	—	Yes	Yes	Yes	—	Yes	Yes <sup>(4)</sup>	Yes

**Notes to Table 1:**

- (1) C = Commercial temperature grade; I = Industrial temperature grade.  
 (2) Lower number refers to faster speed grade.  
 (3) C2L, I2L, and I3L speed grades are for low-power devices.  
 (4) I3YY speed grades can achieve up to 10.3125 Gbps.

Table 2 lists the industrial and commercial speed grades for the Stratix V GT devices.

**Table 2. Stratix V GT Commercial and Industrial Speed Grade Offering <sup>(1), (2)</sup>**

Transceiver Speed Grade	Core Speed Grade			
	C1	C2	I2	I3
2 GX channel—12.5 Gbps GT channel—28.05 Gbps	Yes	Yes	—	—
3 GX channel—12.5 Gbps GT channel—25.78 Gbps	Yes	Yes	Yes	Yes

**Notes to Table 2:**

- (1) C = Commercial temperature grade; I = Industrial temperature grade.  
 (2) Lower number refers to faster speed grade.

**Absolute Maximum Ratings**

Absolute maximum ratings define the maximum operating conditions for Stratix V devices. The values are based on experiments conducted with the devices and theoretical modeling of breakdown and damage mechanisms. The functional operation of the device is not implied for these conditions.



Conditions other than those listed in Table 3 may cause permanent damage to the device. Additionally, device operation at the absolute maximum ratings for extended periods of time may have adverse effects on the device.

**Table 3. Absolute Maximum Ratings for Stratix V Devices (Part 1 of 2)**

Symbol	Description	Minimum	Maximum	Unit
V <sub>CC</sub>	Power supply for core voltage and periphery circuitry	−0.5	1.35	V
V <sub>CCPT</sub>	Power supply for programmable power technology	−0.5	1.8	V
V <sub>CCPGM</sub>	Power supply for configuration pins	−0.5	3.9	V
V <sub>CC_AUX</sub>	Auxiliary supply for the programmable power technology	−0.5	3.4	V
V <sub>CCBAT</sub>	Battery back-up power supply for design security volatile key register	−0.5	3.9	V
V <sub>CCPD</sub>	I/O pre-driver power supply	−0.5	3.9	V
V <sub>CCIO</sub>	I/O power supply	−0.5	3.9	V

## Recommended Operating Conditions

This section lists the functional operating limits for the AC and DC parameters for Stratix V devices. Table 6 lists the steady-state voltage and current values expected from Stratix V devices. Power supply ramps must all be strictly monotonic, without plateaus.

**Table 6. Recommended Operating Conditions for Stratix V Devices (Part 1 of 2)**

Symbol	Description	Condition	Min <sup>(4)</sup>	Typ	Max <sup>(4)</sup>	Unit
V <sub>CC</sub>	Core voltage and periphery circuitry power supply (C1, C2, I2, and I3YY speed grades)	—	0.87	0.9	0.93	V
	Core voltage and periphery circuitry power supply (C2L, C3, C4, I2L, I3, I3L, and I4 speed grades) <sup>(3)</sup>	—	0.82	0.85	0.88	V
V <sub>CCPT</sub>	Power supply for programmable power technology	—	1.45	1.50	1.55	V
V <sub>CC_AUX</sub>	Auxiliary supply for the programmable power technology	—	2.375	2.5	2.625	V
V <sub>CCPD</sub> <sup>(1)</sup>	I/O pre-driver (3.0 V) power supply	—	2.85	3.0	3.15	V
	I/O pre-driver (2.5 V) power supply	—	2.375	2.5	2.625	V
V <sub>CCIO</sub>	I/O buffers (3.0 V) power supply	—	2.85	3.0	3.15	V
	I/O buffers (2.5 V) power supply	—	2.375	2.5	2.625	V
	I/O buffers (1.8 V) power supply	—	1.71	1.8	1.89	V
	I/O buffers (1.5 V) power supply	—	1.425	1.5	1.575	V
	I/O buffers (1.35 V) power supply	—	1.283	1.35	1.45	V
	I/O buffers (1.25 V) power supply	—	1.19	1.25	1.31	V
	I/O buffers (1.2 V) power supply	—	1.14	1.2	1.26	V
V <sub>CCPGM</sub>	Configuration pins (3.0 V) power supply	—	2.85	3.0	3.15	V
	Configuration pins (2.5 V) power supply	—	2.375	2.5	2.625	V
	Configuration pins (1.8 V) power supply	—	1.71	1.8	1.89	V
V <sub>CCA_FPLL</sub>	PLL analog voltage regulator power supply	—	2.375	2.5	2.625	V
V <sub>CCD_FPLL</sub>	PLL digital voltage regulator power supply	—	1.45	1.5	1.55	V
V <sub>CCBAT</sub> <sup>(2)</sup>	Battery back-up power supply (For design security volatile key register)	—	1.2	—	3.0	V
V <sub>I</sub>	DC input voltage	—	−0.5	—	3.6	V
V <sub>O</sub>	Output voltage	—	0	—	V <sub>CCIO</sub>	V
T <sub>J</sub>	Operating junction temperature	Commercial	0	—	85	°C
		Industrial	−40	—	100	°C

**Table 13. OCT Variation after Power-Up Calibration for Stratix V Devices (Part 2 of 2) <sup>(1)</sup>**

Symbol	Description	V <sub>CCIO</sub> (V)	Typical	Unit
dR/dT	OCT variation with temperature without recalibration	3.0	0.189	%/ <sup>o</sup> C
		2.5	0.208	
		1.8	0.266	
		1.5	0.273	
		1.2	0.317	

**Note to Table 13:**

(1) Valid for a V<sub>CCIO</sub> range of  $\pm 5\%$  and a temperature range of 0° to 85°C.

**Pin Capacitance**

Table 14 lists the Stratix V device family pin capacitance.

**Table 14. Pin Capacitance for Stratix V Devices**

Symbol	Description	Value	Unit
C <sub>IOTB</sub>	Input capacitance on the top and bottom I/O pins	6	pF
C <sub>IOLR</sub>	Input capacitance on the left and right I/O pins	6	pF
C <sub>OUTFB</sub>	Input capacitance on dual-purpose clock output and feedback pins	6	pF

**Hot Socketing**

Table 15 lists the hot socketing specifications for Stratix V devices.

**Table 15. Hot Socketing Specifications for Stratix V Devices**

Symbol	Description	Maximum
I <sub>IOPIN</sub> (DC)	DC current per I/O pin	300 $\mu$ A
I <sub>IOPIN</sub> (AC)	AC current per I/O pin	8 mA <sup>(1)</sup>
I <sub>XCVR-TX</sub> (DC)	DC current per transceiver transmitter pin	100 mA
I <sub>XCVR-RX</sub> (DC)	DC current per transceiver receiver pin	50 mA

**Note to Table 15:**

(1) The I/O ramp rate is 10 ns or more. For ramp rates faster than 10 ns,  $|I_{IOPIN}| = C \, dv/dt$ , in which C is the I/O pin capacitance and dv/dt is the slew rate.

**Table 23. Transceiver Specifications for Stratix V GX and GS Devices <sup>(1)</sup> (Part 4 of 7)**

Symbol/ Description	Conditions	Transceiver Speed Grade 1			Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Differential on-chip termination resistors <sup>(21)</sup>	85-Ω setting	—	85 ± 30%	—	—	85 ± 30%	—	—	85 ± 30%	—	Ω
	100-Ω setting	—	100 ± 30%	—	—	100 ± 30%	—	—	100 ± 30%	—	Ω
	120-Ω setting	—	120 ± 30%	—	—	120 ± 30%	—	—	120 ± 30%	—	Ω
	150-Ω setting	—	150 ± 30%	—	—	150 ± 30%	—	—	150 ± 30%	—	Ω
V <sub>ICM</sub> (AC and DC coupled)	V <sub>CCR_GXB</sub> = 0.85 V or 0.9 V full bandwidth	—	600	—	—	600	—	—	600	—	mV
	V <sub>CCR_GXB</sub> = 0.85 V or 0.9 V half bandwidth	—	600	—	—	600	—	—	600	—	mV
	V <sub>CCR_GXB</sub> = 1.0 V/1.05 V full bandwidth	—	700	—	—	700	—	—	700	—	mV
	V <sub>CCR_GXB</sub> = 1.0 V half bandwidth	—	750	—	—	750	—	—	750	—	mV
t <sub>LTR</sub> <sup>(11)</sup>	—	—	—	10	—	—	10	—	—	10	μs
t <sub>LTD</sub> <sup>(12)</sup>	—	4	—	—	4	—	—	4	—	—	μs
t <sub>LTD_manual</sub> <sup>(13)</sup>	—	4	—	—	4	—	—	4	—	—	μs
t <sub>LTR_LTD_manual</sub> <sup>(14)</sup>	—	15	—	—	15	—	—	15	—	—	μs
Run Length	—	—	—	200	—	—	200	—	—	200	UI
Programmable equalization (AC Gain) <sup>(10)</sup>	Full bandwidth (6.25 GHz) Half bandwidth (3.125 GHz)	—	—	16	—	—	16	—	—	16	dB

**Table 28. Transceiver Specifications for Stratix V GT Devices (Part 3 of 5) <sup>(1)</sup>**

Symbol/ Description	Conditions	Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	
Differential on-chip termination resistors <sup>(7)</sup>	GT channels	—	100	—	—	100	—	$\Omega$
Differential on-chip termination resistors for GX channels <sup>(19)</sup>	85- $\Omega$ setting	—	85 $\pm$ 30%	—	—	85 $\pm$ 30%	—	$\Omega$
	100- $\Omega$ setting	—	100 $\pm$ 30%	—	—	100 $\pm$ 30%	—	$\Omega$
	120- $\Omega$ setting	—	120 $\pm$ 30%	—	—	120 $\pm$ 30%	—	$\Omega$
	150- $\Omega$ setting	—	150 $\pm$ 30%	—	—	150 $\pm$ 30%	—	$\Omega$
V <sub>ICM</sub> (AC coupled)	GT channels	—	650	—	—	650	—	mV
VICM (AC and DC coupled) for GX Channels	VCCR_GXB = 0.85 V or 0.9 V	—	600	—	—	600	—	mV
	VCCR_GXB = 1.0 V full bandwidth	—	700	—	—	700	—	mV
	VCCR_GXB = 1.0 V half bandwidth	—	750	—	—	750	—	mV
t <sub>LTR</sub> <sup>(9)</sup>	—	—	—	10	—	—	10	$\mu$ s
t <sub>LTD</sub> <sup>(10)</sup>	—	4	—	—	4	—	—	$\mu$ s
t <sub>LTD_manual</sub> <sup>(11)</sup>	—	4	—	—	4	—	—	$\mu$ s
t <sub>LTR_LTD_manual</sub> <sup>(12)</sup>	—	15	—	—	15	—	—	$\mu$ s
Run Length	GT channels	—	—	72	—	—	72	CID
	GX channels	<sup>(8)</sup>						
CDR PPM	GT channels	—	—	1000	—	—	1000	$\pm$ PPM
	GX channels	<sup>(8)</sup>						
Programmable equalization (AC Gain) <sup>(5)</sup>	GT channels	—	—	14	—	—	14	dB
	GX channels	<sup>(8)</sup>						
Programmable DC gain <sup>(6)</sup>	GT channels	—	—	7.5	—	—	7.5	dB
	GX channels	<sup>(8)</sup>						
Differential on-chip termination resistors <sup>(7)</sup>	GT channels	—	100	—	—	100	—	$\Omega$
<b>Transmitter</b>								
Supported I/O Standards	—	1.4-V and 1.5-V PCML						
Data rate (Standard PCS)	GX channels	600	—	8500	600	—	8500	Mbps
Data rate (10G PCS)	GX channels	600	—	12,500	600	—	12,500	Mbps

Figure 6 shows the Stratix V DC gain curves for GT channels.

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**Figure 6. DC Gain Curves for GT Channels**

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**Transceiver Characterization**

This section summarizes the Stratix V transceiver characterization results for compliance with the following protocols:

- Interlaken
- 40G (XLAUI)/100G (CAUI)
- 10GBase-KR
- QSGMII
- XAUI
- SFI
- Gigabit Ethernet (Gbe / GIGE)
- SPAUI
- Serial Rapid IO (SRIO)
- CPRI
- OBSAI
- Hyper Transport (HT)
- SATA
- SAS
- CEI

**Table 31. PLL Specifications for Stratix V Devices (Part 2 of 3)**

Symbol	Parameter	Min	Typ	Max	Unit
$t_{\text{INCCJ}}$ <sup>(3), (4)</sup>	Input clock cycle-to-cycle jitter ( $f_{\text{REF}} \geq 100$ MHz)	—	—	0.15	UI (p-p)
	Input clock cycle-to-cycle jitter ( $f_{\text{REF}} < 100$ MHz)	−750	—	+750	ps (p-p)
$t_{\text{OUTPJ\_DC}}$ <sup>(5)</sup>	Period Jitter for dedicated clock output ( $f_{\text{OUT}} \geq 100$ MHz)	—	—	175 <sup>(1)</sup>	ps (p-p)
	Period Jitter for dedicated clock output ( $f_{\text{OUT}} < 100$ MHz)	—	—	17.5 <sup>(1)</sup>	mUI (p-p)
$t_{\text{FOUTPJ\_DC}}$ <sup>(5)</sup>	Period Jitter for dedicated clock output in fractional PLL ( $f_{\text{OUT}} \geq 100$ MHz)	—	—	250 <sup>(11)</sup> , 175 <sup>(12)</sup>	ps (p-p)
	Period Jitter for dedicated clock output in fractional PLL ( $f_{\text{OUT}} < 100$ MHz)	—	—	25 <sup>(11)</sup> , 17.5 <sup>(12)</sup>	mUI (p-p)
$t_{\text{OUTCCJ\_DC}}$ <sup>(5)</sup>	Cycle-to-Cycle Jitter for a dedicated clock output ( $f_{\text{OUT}} \geq 100$ MHz)	—	—	175	ps (p-p)
	Cycle-to-Cycle Jitter for a dedicated clock output ( $f_{\text{OUT}} < 100$ MHz)	—	—	17.5	mUI (p-p)
$t_{\text{FOUTCCJ\_DC}}$ <sup>(5)</sup>	Cycle-to-cycle Jitter for a dedicated clock output in fractional PLL ( $f_{\text{OUT}} \geq 100$ MHz)	—	—	250 <sup>(11)</sup> , 175 <sup>(12)</sup>	ps (p-p)
	Cycle-to-cycle Jitter for a dedicated clock output in fractional PLL ( $f_{\text{OUT}} < 100$ MHz)+	—	—	25 <sup>(11)</sup> , 17.5 <sup>(12)</sup>	mUI (p-p)
$t_{\text{OUTPJ\_IO}}$ <sup>(5), (8)</sup>	Period Jitter for a clock output on a regular I/O in integer PLL ( $f_{\text{OUT}} \geq 100$ MHz)	—	—	600	ps (p-p)
	Period Jitter for a clock output on a regular I/O ( $f_{\text{OUT}} < 100$ MHz)	—	—	60	mUI (p-p)
$t_{\text{FOUTPJ\_IO}}$ <sup>(5), (8), (11)</sup>	Period Jitter for a clock output on a regular I/O in fractional PLL ( $f_{\text{OUT}} \geq 100$ MHz)	—	—	600 <sup>(10)</sup>	ps (p-p)
	Period Jitter for a clock output on a regular I/O in fractional PLL ( $f_{\text{OUT}} < 100$ MHz)	—	—	60 <sup>(10)</sup>	mUI (p-p)
$t_{\text{OUTCCJ\_IO}}$ <sup>(5), (8)</sup>	Cycle-to-cycle Jitter for a clock output on a regular I/O in integer PLL ( $f_{\text{OUT}} \geq 100$ MHz)	—	—	600	ps (p-p)
	Cycle-to-cycle Jitter for a clock output on a regular I/O in integer PLL ( $f_{\text{OUT}} < 100$ MHz)	—	—	60 <sup>(10)</sup>	mUI (p-p)
$t_{\text{FOUTCCJ\_IO}}$ <sup>(5), (8), (11)</sup>	Cycle-to-cycle Jitter for a clock output on a regular I/O in fractional PLL ( $f_{\text{OUT}} \geq 100$ MHz)	—	—	600 <sup>(10)</sup>	ps (p-p)
	Cycle-to-cycle Jitter for a clock output on a regular I/O in fractional PLL ( $f_{\text{OUT}} < 100$ MHz)	—	—	60	mUI (p-p)
$t_{\text{CASC\_OUTPJ\_DC}}$ <sup>(5), (6)</sup>	Period Jitter for a dedicated clock output in cascaded PLLs ( $f_{\text{OUT}} \geq 100$ MHz)	—	—	175	ps (p-p)
	Period Jitter for a dedicated clock output in cascaded PLLs ( $f_{\text{OUT}} < 100$ MHz)	—	—	17.5	mUI (p-p)
$f_{\text{DRIFT}}$	Frequency drift after PFDENA is disabled for a duration of 100 $\mu$ s	—	—	$\pm 10$	%
$dK_{\text{BIT}}$	Bit number of Delta Sigma Modulator (DSM)	8	24	32	Bits
$k_{\text{VALUE}}$	Numerator of Fraction	128	8388608	2147483648	—



## Periphery Performance

This section describes periphery performance, including high-speed I/O and external memory interface.

I/O performance supports several system interfaces, such as the **LVDS** high-speed I/O interface, external memory interface, and the **PCI/PCI-X** bus interface.

General-purpose I/O standards such as 3.3-, 2.5-, 1.8-, and 1.5-**LVTTL/LVCMOS** are capable of a typical 167 MHz and 1.2-**LVCMOS** at 100 MHz interfacing frequency with a 10 pF load.



The actual achievable frequency depends on design- and system-specific factors. Ensure proper timing closure in your design and perform HSPICE/IBIS simulations based on your specific design and system setup to determine the maximum achievable frequency in your system.

### High-Speed I/O Specification

Table 36 lists high-speed I/O timing for Stratix V devices.

**Table 36. High-Speed I/O Specifications for Stratix V Devices <sup>(1)</sup>, <sup>(2)</sup> (Part 1 of 4)**

Symbol	Conditions	C1			C2, C2L, I2, I2L			C3, I3, I3L, I3YY			C4,I4			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$f_{\text{HCLK\_in}}$ (input clock frequency) True Differential I/O Standards	Clock boost factor $W = 1$ to 40 <sup>(4)</sup>	5	—	800	5	—	800	5	—	625	5	—	525	MHz
$f_{\text{HCLK\_in}}$ (input clock frequency) Single Ended I/O Standards <sup>(3)</sup>	Clock boost factor $W = 1$ to 40 <sup>(4)</sup>	5	—	800	5	—	800	5	—	625	5	—	525	MHz
$f_{\text{HCLK\_in}}$ (input clock frequency) Single Ended I/O Standards	Clock boost factor $W = 1$ to 40 <sup>(4)</sup>	5	—	520	5	—	520	5	—	420	5	—	420	MHz
$f_{\text{HCLK\_OUT}}$ (output clock frequency)	—	5	—	800	5	—	800	5	—	625 <sup>(5)</sup>	5	—	525 <sup>(5)</sup>	MHz

**Table 36. High-Speed I/O Specifications for Stratix V Devices <sup>(1)</sup>, <sup>(2)</sup> (Part 3 of 4)**

Symbol	Conditions	C1			C2, C2L, I2, I2L			C3, I3, I3L, I3YY			C4, I4			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$t_{DUTY}$	Transmitter output clock duty cycle for both True and Emulated Differential I/O Standards	45	50	55	45	50	55	45	50	55	45	50	55	%
$t_{RISE}$ & $t_{FALL}$	True Differential I/O Standards	—	—	160	—	—	160	—	—	200	—	—	200	ps
	Emulated Differential I/O Standards with three external output resistor networks	—	—	250	—	—	250	—	—	250	—	—	300	ps
TCCS	True Differential I/O Standards	—	—	150	—	—	150	—	—	150	—	—	150	ps
	Emulated Differential I/O Standards	—	—	300	—	—	300	—	—	300	—	—	300	ps
<b>Receiver</b>														
True Differential I/O Standards - $f_{HSDRDPA}$ (data rate)	SERDES factor J = 3 to 10 <sup>(11)</sup> , <sup>(12)</sup> , <sup>(13)</sup> , <sup>(14)</sup> , <sup>(15)</sup> , <sup>(16)</sup>	150	—	1434	150	—	1434	150	—	1250	150	—	1050	Mbps
	SERDES factor J $\geq 4$	150	—	1600	150	—	1600	150	—	1600	150	—	1250	Mbps
	LVDS RX with DPA <sup>(12)</sup> , <sup>(14)</sup> , <sup>(15)</sup> , <sup>(16)</sup>	150	—	1600	150	—	1600	150	—	1600	150	—	1250	Mbps
	SERDES factor J = 2, uses DDR Registers	<sup>(6)</sup>	—	<sup>(7)</sup>	<sup>(6)</sup>	—	<sup>(7)</sup>	<sup>(6)</sup>	—	<sup>(7)</sup>	<sup>(6)</sup>	—	<sup>(7)</sup>	Mbps
	SERDES factor J = 1, uses SDR Register	<sup>(6)</sup>	—	<sup>(7)</sup>	<sup>(6)</sup>	—	<sup>(7)</sup>	<sup>(6)</sup>	—	<sup>(7)</sup>	<sup>(6)</sup>	—	<sup>(7)</sup>	Mbps

**Table 36. High-Speed I/O Specifications for Stratix V Devices <sup>(1), (2)</sup> (Part 4 of 4)**

Symbol	Conditions	C1			C2, C2L, I2, I2L			C3, I3, I3L, I3YY			C4, I4			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
f <sub>HSDR</sub> (data rate)	SERDES factor J = 3 to 10	(6)	—	(8)	(6)	—	(8)	(6)	—	(8)	(6)	—	(8)	Mbps
	SERDES factor J = 2, uses DDR Registers	(6)	—	(7)	(6)	—	(7)	(6)	—	(7)	(6)	—	(7)	Mbps
	SERDES factor J = 1, uses SDR Register	(6)	—	(7)	(6)	—	(7)	(6)	—	(7)	(6)	—	(7)	Mbps
<b>DPA Mode</b>														
DPA run length	—	—	—	1000 0	—	—	1000 0	—	—	1000 0	—	—	1000 0	UI
<b>Soft CDR mode</b>														
Soft-CDR PPM tolerance	—	—	—	300	—	—	300	—	—	300	—	—	300	± PPM
<b>Non DPA Mode</b>														
Sampling Window	—	—	—	300	—	—	300	—	—	300	—	—	300	ps

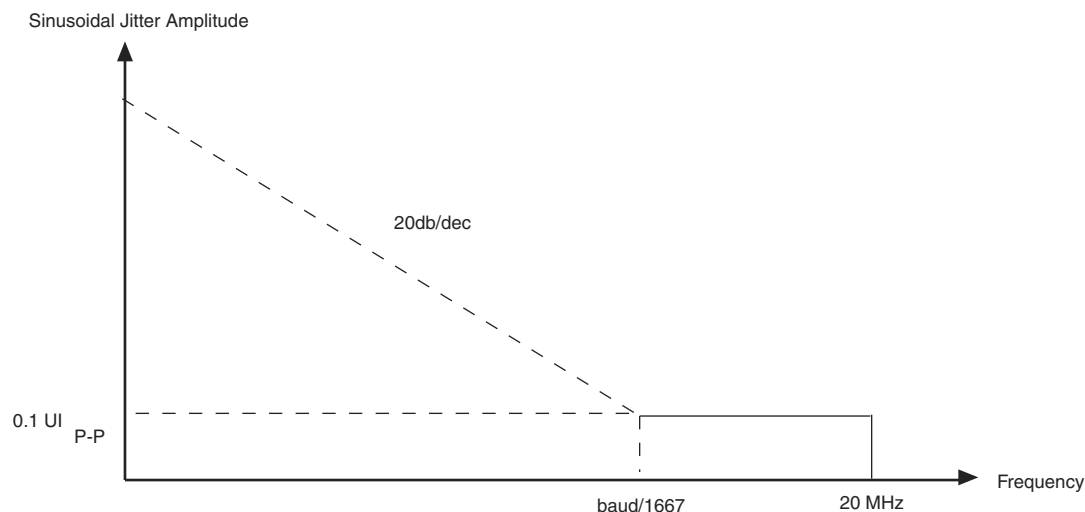
**Notes to Table 36:**

- (1) When J = 3 to 10, use the serializer/deserializer (SERDES) block.
- (2) When J = 1 or 2, bypass the SERDES block.
- (3) This only applies to DPA and soft-CDR modes.
- (4) Clock Boost Factor (W) is the ratio between the input data rate to the input clock rate.
- (5) This is achieved by using the **LVDS** clock network.
- (6) The minimum specification depends on the clock source (for example, the PLL and clock pin) and the clock routing resource (global, regional, or local) that you use. The I/O differential buffer and input register do not have a minimum toggle rate.
- (7) The maximum ideal frequency is the SERDES factor (J) x the PLL maximum output frequency (f<sub>OUT</sub>) provided you can close the design timing and the signal integrity simulation is clean.
- (8) You can estimate the achievable maximum data rate for non-DPA mode by performing link timing closure analysis. You must consider the board skew margin, transmitter delay margin, and receiver sampling margin to determine the maximum data rate supported.
- (9) If the receiver with DPA enabled and transmitter are using shared PLLs, the minimum data rate is 150 Mbps.
- (10) You must calculate the leftover timing margin in the receiver by performing link timing closure analysis. You must consider the board skew margin, transmitter channel-to-channel skew, and receiver sampling margin to determine leftover timing margin.
- (11) The F<sub>MAX</sub> specification is based on the fast clock used for serial data. The interface F<sub>MAX</sub> is also dependent on the parallel clock domain which is design-dependent and requires timing analysis.
- (12) Stratix V RX LVDS will need DPA. For Stratix V TX LVDS, the receiver side component must have DPA.
- (13) Stratix V LVDS serialization and de-serialization factor needs to be x4 and above.
- (14) Requires package skew compensation with PCB trace length.
- (15) Do not mix single-ended I/O buffer within LVDS I/O bank.
- (16) Chip-to-chip communication only with a maximum load of 5 pF.
- (17) When using True LVDS RX channels for emulated LVDS TX channel, only serialization factors 1 and 2 are supported.

**Table 38. LVDS Soft-CDR/DPA Sinusoidal Jitter Mask Values for a Data Rate  $\geq 1.25$  Gbps**

Jitter Frequency (Hz)		Sinusoidal Jitter (UI)
F1	10,000	25.000
F2	17,565	25.000
F3	1,493,000	0.350
F4	50,000,000	0.350

Figure 9 shows the LVDS soft-CDR/DPA sinusoidal jitter tolerance specification for a data rate  $< 1.25$  Gbps.

**Figure 9. LVDS Soft-CDR/DPA Sinusoidal Jitter Tolerance Specification for a Data Rate  $< 1.25$  Gbps**

### DLL Range, DQS Logic Block, and Memory Output Clock Jitter Specifications

Table 39 lists the DLL range specification for Stratix V devices. The DLL is always in 8-tap mode in Stratix V devices.

**Table 39. DLL Range Specifications for Stratix V Devices <sup>(1)</sup>**

C1	C2, C2L, I2, I2L	C3, I3, I3L, I3YY	C4,I4	Unit
300-933	300-933	300-890	300-890	MHz

**Note to Table 39:**

- (1) Stratix V devices support memory interface frequencies lower than 300 MHz, although the reference clock that feeds the DLL must be at least 300 MHz. To support interfaces below 300 MHz, multiply the reference clock feeding the DLL to ensure the frequency is within the supported range of the DLL.

Table 40 lists the DQS phase offset delay per stage for Stratix V devices.

**Table 40. DQS Phase Offset Delay Per Setting for Stratix V Devices <sup>(1), (2)</sup> (Part 1 of 2)**

Speed Grade	Min	Max	Unit
C1	8	14	ps
C2, C2L, I2, I2L	8	14	ps
C3,I3, I3L, I3YY	8	15	ps

**Table 40. DQS Phase Offset Delay Per Setting for Stratix V Devices <sup>(1), (2)</sup> (Part 2 of 2)**

Speed Grade	Min	Max	Unit
C4,I4	8	16	ps

**Notes to Table 40:**

- (1) The typical value equals the average of the minimum and maximum values.
- (2) The delay settings are linear with a cumulative delay variation of 40 ps for all speed grades. For example, when using a –2 speed grade and applying a 10-phase offset setting to a 90° phase shift at 400 MHz, the expected average cumulative delay is  $[625 \text{ ps} + (10 \times 10 \text{ ps}) \pm 20 \text{ ps}] = 725 \text{ ps} \pm 20 \text{ ps}$ .

Table 41 lists the DQS phase shift error for Stratix V devices.

**Table 41. DQS Phase Shift Error Specification for DLL-Delayed Clock ( $t_{\text{DQS\_PSERR}}$ ) for Stratix V Devices <sup>(1)</sup>**

Number of DQS Delay Buffers	C1	C2, C2L, I2, I2L	C3, I3, I3L, I3YY	C4,I4	Unit
1	28	28	30	32	ps
2	56	56	60	64	ps
3	84	84	90	96	ps
4	112	112	120	128	ps

**Notes to Table 41:**

- (1) This error specification is the absolute maximum and minimum error. For example, skew on three DQS delay buffers in a –2 speed grade is  $\pm 78 \text{ ps}$  or  $\pm 39 \text{ ps}$ .

Table 42 lists the memory output clock jitter specifications for Stratix V devices.

**Table 42. Memory Output Clock Jitter Specification for Stratix V Devices <sup>(1), (Part 1 of 2)</sup> <sup>(2), (3)</sup>**

Clock Network	Parameter	Symbol	C1		C2, C2L, I2, I2L		C3, I3, I3L, I3YY		C4,I4		Unit
			Min	Max	Min	Max	Min	Max	Min	Max	
Regional	Clock period jitter	$t_{\text{JIT(per)}}$	–50	50	–50	50	–55	55	–55	55	ps
	Cycle-to-cycle period jitter	$t_{\text{JIT(cc)}}$	–100	100	–100	100	–110	110	–110	110	ps
	Duty cycle jitter	$t_{\text{JIT(duty)}}$	–50	50	–50	50	–82.5	82.5	–82.5	82.5	ps
Global	Clock period jitter	$t_{\text{JIT(per)}}$	–75	75	–75	75	–82.5	82.5	–82.5	82.5	ps
	Cycle-to-cycle period jitter	$t_{\text{JIT(cc)}}$	–150	150	–150	150	–165	165	–165	165	ps
	Duty cycle jitter	$t_{\text{JIT(duty)}}$	–75	75	–75	75	–90	90	–90	90	ps

**Table 42. Memory Output Clock Jitter Specification for Stratix V Devices <sup>(1)</sup>, (Part 2 of 2) <sup>(2)</sup>, <sup>(3)</sup>**

Clock Network	Parameter	Symbol	C1		C2, C2L, I2, I2L		C3, I3, I3L, I3YY		C4,I4		Unit
			Min	Max	Min	Max	Min	Max	Min	Max	
PHY Clock	Clock period jitter	$t_{JIT(per)}$	-25	25	-25	25	-30	30	-35	35	ps
	Cycle-to-cycle period jitter	$t_{JIT(cc)}$	-50	50	-50	50	-60	60	-70	70	ps
	Duty cycle jitter	$t_{JIT(duty)}$	-37.5	37.5	-37.5	37.5	-45	45	-56	56	ps

**Notes to Table 42:**

- (1) The clock jitter specification applies to the memory output clock pins generated using differential signal-splitter and DDIO circuits clocked by a PLL output routed on a PHY, regional, or global clock network as specified. Altera recommends using PHY clock networks whenever possible.
- (2) The clock jitter specification applies to the memory output clock pins clocked by an integer PLL.
- (3) The memory output clock jitter is applicable when an input jitter of 30 ps peak-to-peak is applied with bit error rate (BER) -12, equivalent to 14 sigma.

**OCT Calibration Block Specifications**

Table 43 lists the OCT calibration block specifications for Stratix V devices.

**Table 43. OCT Calibration Block Specifications for Stratix V Devices**

Symbol	Description	Min	Typ	Max	Unit
OCTUSRCLK	Clock required by the OCT calibration blocks	—	—	20	MHz
$T_{OCTCAL}$	Number of OCTUSRCLK clock cycles required for OCT $R_S/R_T$ calibration	—	1000	—	Cycles
$T_{OCTSHIFT}$	Number of OCTUSRCLK clock cycles required for the OCT code to shift out	—	32	—	Cycles
$T_{RS\_RT}$	Time required between the <code>dyn_term_ctrl</code> and <code>oe</code> signal transitions in a bidirectional I/O buffer to dynamically switch between OCT $R_S$ and $R_T$ (Figure 10)	—	2.5	—	ns

Figure 10 shows the timing diagram for the `oe` and `dyn_term_ctrl` signals.

**Figure 10. Timing Diagram for `oe` and `dyn_term_ctrl` Signals**

**Table 49. DCLK-to-DATA[] Ratio <sup>(1)</sup> (Part 2 of 2)**

Configuration Scheme	Decompression	Design Security	DCLK-to-DATA[] Ratio
FPP ×32	Disabled	Disabled	1
	Disabled	Enabled	4
	Enabled	Disabled	8
	Enabled	Enabled	8

**Note to Table 49:**

- (1) Depending on the DCLK-to-DATA[] ratio, the host must send a DCLK frequency that is r times the data rate in bytes per second (Bps), or words per second (Wps). For example, in FPP ×16 when the DCLK-to-DATA[] ratio is 2, the DCLK frequency must be 2 times the data rate in Wps. Stratix V devices use the additional clock cycles to decrypt and decompress the configuration data.



If the DCLK-to-DATA[] ratio is greater than 1, at the end of configuration, you can only stop the DCLK (DCLK-to-DATA[] ratio – 1) clock cycles after the last data is latched into the Stratix V device.

Figure 11 shows the configuration interface connections between the Stratix V device and a MAX II or MAX V device for single device configuration.

**Figure 11. Single Device FPP Configuration Using an External Host****Notes to Figure 11:**

- (1) Connect the resistor to a supply that provides an acceptable input signal for the Stratix V device.  $V_{CCPGM}$  must be high enough to meet the  $V_{IH}$  specification of the I/O on the device and the external host. Altera recommends powering up all configuration system I/Os with  $V_{CCPGM}$ .
- (2) You can leave the nCEO pin unconnected or use it as a user I/O pin when it does not feed another device's nCE pin.
- (3) The MSEL pin settings vary for different data width, configuration voltage standards, and POR delay. To connect MSEL, refer to the MSEL Pin Settings section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (4) If you use FPP ×8, use DATA[7..0]. If you use FPP ×16, use DATA[15..0].

## Active Serial Configuration Timing

Table 52 lists the DCLK frequency specification in the AS configuration scheme.

**Table 52. DCLK Frequency Specification in the AS Configuration Scheme <sup>(1), (2)</sup>**

Minimum	Typical	Maximum	Unit
5.3	7.9	12.5	MHz
10.6	15.7	25.0	MHz
21.3	31.4	50.0	MHz
42.6	62.9	100.0	MHz

**Notes to Table 52:**

- (1) This applies to the DCLK frequency specification when using the internal oscillator as the configuration clock source.
- (2) The AS multi-device configuration scheme does not support DCLK frequency of 100 MHz.

Figure 14 shows the single-device configuration setup for an AS ×1 mode.

**Figure 14. AS Configuration Timing**



**Notes to Figure 14:**

- (1) If you are using AS ×4 mode, this signal represents the AS\_DATA [3 : 0] and EPCQ sends in 4-bits of data for each DCLK cycle.
- (2) The initialization clock can be from internal oscillator or CLKUSR pin.
- (3) After the option bit to enable the INIT\_DONE pin is configured into the device, the INIT\_DONE goes low.

Table 53 lists the timing parameters for AS ×1 and AS ×4 configurations in Stratix V devices.

**Table 53. AS Timing Parameters for AS ×1 and AS ×4 Configurations in Stratix V Devices <sup>(1), (2)</sup> (Part 1 of 2)**

Symbol	Parameter	Minimum	Maximum	Units
$t_{CO}$	DCLK falling edge to AS_DATA0/ASDO output	—	2	ns
$t_{SU}$	Data setup time before falling edge on DCLK	1.5	—	ns
$t_H$	Data hold time after falling edge on DCLK	0	—	ns



Table 54 lists the PS configuration timing parameters for Stratix V devices.

**Table 54. PS Timing Parameters for Stratix V Devices**

Symbol	Parameter	Minimum	Maximum	Units
$t_{CF2CD}$	nCONFIG low to CONF_DONE low	—	600	ns
$t_{CF2ST0}$	nCONFIG low to nSTATUS low	—	600	ns
$t_{CFG}$	nCONFIG low pulse width	2	—	$\mu$ s
$t_{STATUS}$	nSTATUS low pulse width	268	1,506 <sup>(1)</sup>	$\mu$ s
$t_{CF2ST1}$	nCONFIG high to nSTATUS high	—	1,506 <sup>(2)</sup>	$\mu$ s
$t_{CF2CK}$ <sup>(5)</sup>	nCONFIG high to first rising edge on DCLK	1,506	—	$\mu$ s
$t_{ST2CK}$ <sup>(5)</sup>	nSTATUS high to first rising edge of DCLK	2	—	$\mu$ s
$t_{DSU}$	DATA [] setup time before rising edge on DCLK	5.5	—	ns
$t_{DH}$	DATA [] hold time after rising edge on DCLK	0	—	ns
$t_{CH}$	DCLK high time	$0.45 \times 1/f_{MAX}$	—	s
$t_{CL}$	DCLK low time	$0.45 \times 1/f_{MAX}$	—	s
$t_{CLK}$	DCLK period	$1/f_{MAX}$	—	s
$f_{MAX}$	DCLK frequency	—	125	MHz
$t_{CD2UM}$	CONF_DONE high to user mode <sup>(3)</sup>	175	437	$\mu$ s
$t_{CD2CU}$	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	—	—
$t_{CD2UMC}$	CONF_DONE high to user mode with CLKUSR option on	$t_{CD2CU} + (8576 \times \text{CLKUSR period})$ <sup>(4)</sup>	—	—

**Notes to Table 54:**

- (1) This value is applicable if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.
- (2) This value is applicable if you do not delay configuration by externally holding the nSTATUS low.
- (3) The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for initializing the device.
- (4) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the “Initialization” section.
- (5) If nSTATUS is monitored, follow the  $t_{ST2CK}$  specification. If nSTATUS is not monitored, follow the  $t_{CF2CK}$  specification.

## Initialization

Table 55 lists the initialization clock source option, the applicable configuration schemes, and the maximum frequency.

**Table 55. Initialization Clock Source Option and the Maximum Frequency**

Initialization Clock Source	Configuration Schemes	Maximum Frequency	Minimum Number of Clock Cycles <sup>(1)</sup>
Internal Oscillator	AS, PS, FPP	12.5 MHz	8576
CLKUSR	AS, PS, FPP <sup>(2)</sup>	125 MHz	
DCLK	PS, FPP	125 MHz	

**Notes to Table 55:**

- (1) The minimum number of clock cycles required for device initialization.
- (2) To enable CLKUSR as the initialization clock source, turn on the **Enable user-supplied start-up clock (CLKUSR)** option in the Quartus II software from the **General** panel of the **Device and Pin Options** dialog box.

Table 60. Glossary (Part 3 of 4)

Letter	Subject	Definitions
S	SW (sampling window)	<p>Timing Diagram—the period of time during which the data must be valid in order to capture it correctly. The setup and hold times determine the ideal strobe position within the sampling window, as shown:</p> 
	Single-ended voltage referenced I/O standard	<p>The JEDEC standard for <b>SSTL</b> and <b>HSTL</b> I/O defines both the AC and DC input signal values. The AC values indicate the voltage levels at which the receiver must meet its timing specifications. The DC values indicate the voltage levels at which the final logic state of the receiver is unambiguously defined. After the receiver input has crossed the AC value, the receiver changes to the new logic state.</p> <p>The new logic state is then maintained as long as the input stays beyond the DC threshold. This approach is intended to provide predictable receiver timing in the presence of input waveform ringing:</p> <p><i>Single-Ended Voltage Referenced I/O Standard</i></p> 
T	$t_c$	High-speed receiver and transmitter input and output clock period.
	TCCS (channel-to-channel-skew)	The timing difference between the fastest and slowest output edges, including $t_{CO}$ variation and clock skew, across channels driven by the same PLL. The clock is included in the TCCS measurement (refer to the <i>Timing Diagram</i> figure under <b>SW</b> in this table).
	$t_{DUTY}$	<p>High-speed I/O block—Duty cycle on the high-speed transmitter output clock.</p> <p><b>Timing Unit Interval (TUI)</b></p> <p>The timing budget allowed for skew, propagation delays, and the data sampling window. (TUI = <math>1/(\text{receiver input clock frequency multiplication factor}) = t_c/w</math>)</p>
	$t_{FALL}$	Signal high-to-low transition time (80-20%)
	$t_{INCCJ}$	Cycle-to-cycle jitter tolerance on the PLL clock input.
	$t_{OUTPJ\_IO}$	Period jitter on the general purpose I/O driven by a PLL.
	$t_{OUTPJ\_DC}$	Period jitter on the dedicated clock output driven by a PLL.
	$t_{RISE}$	Signal low-to-high transition time (20-80%)
U	—	—

**Table 60. Glossary (Part 4 of 4)**

Letter	Subject	Definitions
<b>V</b>	$V_{CM(DC)}$	DC common mode input voltage.
	$V_{ICM}$	Input common mode voltage—The common mode of the differential signal at the receiver.
	$V_{ID}$	Input differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the receiver.
	$V_{DIF(AC)}$	AC differential input voltage—Minimum AC input differential voltage required for switching.
	$V_{DIF(DC)}$	DC differential input voltage— Minimum DC input differential voltage required for switching.
	$V_{IH}$	Voltage input high—The minimum positive voltage applied to the input which is accepted by the device as a logic high.
	$V_{IH(AC)}$	High-level AC input voltage
	$V_{IH(DC)}$	High-level DC input voltage
	$V_{IL}$	Voltage input low—The maximum positive voltage applied to the input which is accepted by the device as a logic low.
	$V_{IL(AC)}$	Low-level AC input voltage
	$V_{IL(DC)}$	Low-level DC input voltage
	$V_{OCM}$	Output common mode voltage—The common mode of the differential signal at the transmitter.
	$V_{OD}$	Output differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the transmitter.
	$V_{SWING}$	Differential input voltage
	$V_X$	Input differential cross point voltage
	$V_{OX}$	Output differential cross point voltage
<b>W</b>	W	High-speed I/O block—clock boost factor
<b>X</b>	—	—
<b>Y</b>		
<b>Z</b>		

**Table 61. Document Revision History (Part 2 of 3)**

Date	Version	Changes
November 2014	3.3	<ul style="list-style-type: none"> <li>■ Added the I3YY speed grade and changed the data rates for the GX channel in Table 1.</li> <li>■ Added the I3YY speed grade to the <math>V_{CC}</math> description in Table 6.</li> <li>■ Added the I3YY speed grade to <math>V_{CCHIP\_L}</math>, <math>V_{CCHIP\_R}</math>, <math>V_{CCHSSI\_L}</math>, and <math>V_{CCHSSI\_R}</math> descriptions in Table 7.</li> <li>■ Added 240-<math>\Omega</math> to Table 11.</li> <li>■ Changed CDR PPM tolerance in Table 23.</li> <li>■ Added additional max data rate for fPLL in Table 23.</li> <li>■ Added the I3YY speed grade and changed the data rates for transceiver speed grade 3 in Table 25.</li> <li>■ Added the I3YY speed grade and changed the data rates for transceiver speed grade 3 in Table 26.</li> <li>■ Changed CDR PPM tolerance in Table 28.</li> <li>■ Added additional max data rate for fPLL in Table 28.</li> <li>■ Changed the mode descriptions for MLAB and M20K in Table 33.</li> <li>■ Changed the Max value of <math>f_{HCLK\_OUT}</math> for the C2, C2L, I2, I2L speed grades in Table 36.</li> <li>■ Changed the frequency ranges for C1 and C2 in Table 39.</li> <li>■ Changed the .rbf file sizes for 5SGSD6 and 5SGSD8 in Table 47.</li> <li>■ Added note about nSTATUS to Table 50, Table 51, Table 54.</li> <li>■ Changed the available settings in Table 58.</li> <li>■ Changed the note in “Periphery Performance”.</li> <li>■ Updated the “I/O Standard Specifications” section.</li> <li>■ Updated the “Raw Binary File Size” section.</li> <li>■ Updated the receiver voltage input range in Table 22.</li> <li>■ Updated the max frequency for the LVDS clock network in Table 36.</li> <li>■ Updated the DCLK note to Figure 11.</li> <li>■ Updated Table 23 <math>VO_{CM}</math> (DC Coupled) condition.</li> <li>■ Updated Table 6 and Table 7.</li> <li>■ Added the DCLK specification to Table 55.</li> <li>■ Updated the notes for Table 47.</li> <li>■ Updated the list of parameters for Table 56.</li> </ul>
November 2013	3.2	■ Updated Table 28
November 2013	3.1	■ Updated Table 33
November 2013	3.0	■ Updated Table 23 and Table 28
October 2013	2.9	■ Updated the “Transceiver Characterization” section
October 2013	2.8	<ul style="list-style-type: none"> <li>■ Updated Table 3, Table 12, Table 14, Table 19, Table 20, Table 23, Table 24, Table 28, Table 30, Table 31, Table 32, Table 33, Table 36, Table 39, Table 40, Table 41, Table 42, Table 47, Table 53, Table 58, and Table 59</li> <li>■ Added Figure 1 and Figure 3</li> <li>■ Added the “Transceiver Characterization” section</li> <li>■ Removed all “Preliminary” designations.</li> </ul>

**Table 61. Document Revision History (Part 3 of 3)**

Date	Version	Changes
May 2013	2.7	<ul style="list-style-type: none"> <li>■ Updated Table 2, Table 6, Table 7, Table 20, Table 23, Table 27, Table 47, Table 60</li> <li>■ Added Table 24, Table 48</li> <li>■ Updated Figure 9, Figure 10, Figure 11, Figure 12</li> </ul>
February 2013	2.6	<ul style="list-style-type: none"> <li>■ Updated Table 7, Table 9, Table 20, Table 23, Table 27, Table 30, Table 31, Table 35, Table 46</li> <li>■ Updated “Maximum Allowed Overshoot and Undershoot Voltage”</li> </ul>
December 2012	2.5	<ul style="list-style-type: none"> <li>■ Updated Table 3, Table 6, Table 7, Table 8, Table 23, Table 24, Table 25, Table 27, Table 30, Table 32, Table 35</li> <li>■ Added Table 33</li> <li>■ Added “Fast Passive Parallel Configuration Timing”</li> <li>■ Added “Active Serial Configuration Timing”</li> <li>■ Added “Passive Serial Configuration Timing”</li> <li>■ Added “Remote System Upgrades”</li> <li>■ Added “User Watchdog Internal Circuitry Timing Specification”</li> <li>■ Added “Initialization”</li> <li>■ Added “Raw Binary File Size”</li> </ul>
June 2012	2.4	<ul style="list-style-type: none"> <li>■ Added Figure 1, Figure 2, and Figure 3.</li> <li>■ Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table 27, Table 29, Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 41, Table 43, Table 56, and Table 59.</li> <li>■ Various edits throughout to fix bugs.</li> <li>■ Changed title of document to <i>Stratix V Device Datasheet</i>.</li> <li>■ Removed document from the Stratix V handbook and made it a separate document.</li> </ul>
February 2012	2.3	<ul style="list-style-type: none"> <li>■ Updated Table 1–22, Table 1–29, Table 1–31, and Table 1–31.</li> </ul>
December 2011	2.2	<ul style="list-style-type: none"> <li>■ Added Table 2–31.</li> <li>■ Updated Table 2–28 and Table 2–34.</li> </ul>
November 2011	2.1	<ul style="list-style-type: none"> <li>■ Added Table 2–2 and Table 2–21 and updated Table 2–5 with information about Stratix V GT devices.</li> <li>■ Updated Table 2–11, Table 2–13, Table 2–20, and Table 2–25.</li> <li>■ Various edits throughout to fix SPRs.</li> </ul>
May 2011	2.0	<ul style="list-style-type: none"> <li>■ Updated Table 2–4, Table 2–18, Table 2–19, Table 2–21, Table 2–22, Table 2–23, and Table 2–24.</li> <li>■ Updated the “DQ Logic Block and Memory Output Clock Jitter Specifications” title.</li> <li>■ Chapter moved to Volume 1.</li> <li>■ Minor text edits.</li> </ul>
December 2010	1.1	<ul style="list-style-type: none"> <li>■ Updated Table 1–2, Table 1–4, Table 1–19, and Table 1–23.</li> <li>■ Converted chapter to the new template.</li> <li>■ Minor text edits.</li> </ul>
July 2010	1.0	Initial release.